



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of :

Parthasarathy Rajagopalan
Minh Vuong

Serial No. : 09/465,131

Group Art Unit : 2859

Filed : December 16, 1999

Examiner : Guadalupe, Yaritza

For : Method and Apparatus for Thermal
Profiling of Flip-Chip Packages

Atty Docket : 65611 / 99-099/RCE

I hereby certify that this correspondence is being deposited with the U.S.
Postal Service as First Class Mail in an envelope addressed to: Commissioner
for Patents, P. O. Box 1450, Alexandria, VA 22313-1450, on the date below:

Connie Del Castillo

8/16/05

Date

Connie Del Castillo

Signature

SUBMISSION OF FORMAL DRAWINGS PURSUANT TO 37 C.F.R. §1.85

Official Draftsman

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant hereby substitutes the enclosed formal drawings for those presently in the above referenced application.

LSI Logic Corporation
1621 Barber Lane, MS D-106
Milipitas, CA 95035
408-433-7475

Date: 8/16/2005

Respectfully submitted,

Henry Groth

Henry Groth

Reg. No. 39,696